	SPECIFI	CATIONS	
CUSTOMER	:	PTC	
SAMPLE CODE (Ver.)	:		
MASS PRODUCTION CODE	(Ver.)	PC1602ARU-	HWB-G-Q(Rev.0)
DRAWING NO. (Ver.)	:	PC-95005	
	Customer	Approved	
	Customer	Approved Da	ate:
Approved			te: Designer
Approved		Da	
Approved Approved Approval For Specifications Only.		Da	Designer
技術部 2086 6-14 陳稿注	QC Co	Da	Designer
Approval For Specifications Only.	QC Co	Da	Designer
Approval For Specifications Only. * This specification is subject to characteristics.	QC Co	Da	Designer

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RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2006/6/13	0	PC1602ARU-HWB-G-Qis the ROHS compliant part number based on Powertip's standard PC1602ARU-HWB-G		
_				

Total: 19 Page



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Note: For detailed information please refer to IC data sheet: <u>ST7066U,KS0065B</u>



1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	16*2 Characters
LCD Type	STN, YG, Positive, Reflective, Extended Temp.
Driver Condition	LCD Module: 1/16 Duty, 1/5 Bias
Viewing Direction	6 O'clock
Backlight	-
Weight	15 g
Interface	_
Other	_

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	85.0 (L)* 36.0 (W)*10.2 max.(H)	mm
Viewing Area	66.0 (L) *16.2(W)	mm
Active Area	56.21 (L) *11.5(W)	mm
Dot Size	0.56 (L) *0.66(W)	mm
Dot Pitch	0.60 (L) *0.70(W)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	$V_{ m DD}$	_	-0.3	7.0	V
LCD Driver Supply Voltage	V_{LCD}	_	VDD-10.0	V _{DD} +0.3	V
Input Voltage	$V_{\rm IN}$	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T_{OP}	Excluded B/L	-20	70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	Excluded B/L	-30	80	$^{\circ}\mathbb{C}$
Storage Humidity	H_D	Ta<40 ℃	-	90	%RH



1.4 DC Electrical Characteristics

 $V_{DD} = 5.0 \text{ V} \pm 0.5 \text{V}$, $V_{SS} = 0 \text{V}$, $Ta = 25 ^{\circ}\text{C}$

Item	Symbol	Condition	Min.	Туре	Max.	Unit
Logic Supply Voltage	$ m V_{DD}$	_	4.5	5.0	5.5	V
"H" Input Voltage	V_{IH}	_	0.7 Vdd	-	VDD	V
"L" Input Voltage	V_{IL}	_	-0.3	-	0.6	V
"H" Output Voltage	V_{OH}	IOH=-0.1mA	3.9	-	VDD	V
"L" Output Voltage	$V_{ m OL}$	IOL=0.1mA	-	-	0.4	V
Supply Current	I_{DD}	$V_{DD} = 5.0 \text{ V}$	-	1.5	3.0	mA
		-20°C	-	-	-	
LCM Driver Voltage	V_{OP}	25°C *1	5.6	5.8	6.0	V
		70°C	-	-	-	

Note: *1. THE V_{OP} TEST POINT IS V_{DD} - $V_{\text{O}}.$

1.5 Optical Characteristics

LCD Panel : 1/16 Duty , 1/4Bias , $V_{LCD} = 6.0$ V , Ta = 25°C

Item	Symbol	Conditions	Min.	Туре	Max.	Reference
View Angle	θ	$C \ge 2.0, \varnothing = 0^{\circ}$	40°	-	-	Notes 1 & 2
Contrast Ratio	С	$\theta = 5^{\circ}, \varnothing = 0^{\circ}$	5	7	-	Note 3
Response Time(rise)	tr	$\theta = 5^{\circ}, \varnothing = 0^{\circ}$	-	200ms	-	Note 4
Response Time(fall)	tf	$\theta = 5^{\circ}, \varnothing = 0^{\circ}$	-	150 ms	-	Note 4



Note 1: Definition of angles θ and \emptyset

Light (when reflected) $z (\theta=0^{\circ})$

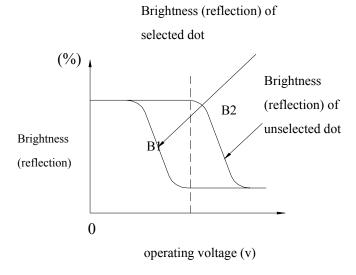
Sensor θ $Y'(\emptyset=180^{\circ})$ X' Z'LCD panel $X(\emptyset=90^{\circ})$

Light (when transmitted) $Y(\varnothing=0^{\circ})$ $(\theta=90^{\circ})$

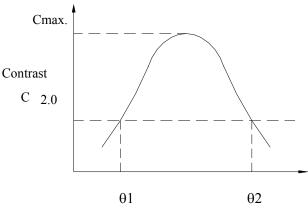
Note 3: Definition of contrast C

Brightness (reflection) of unselected dot (B2)

Brightness (reflection) of selected dot (B1)



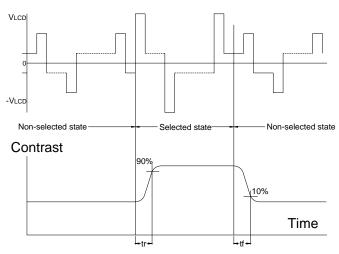
Note 2: Definition of viewing angles $\theta 1$ and $\theta 2$



viewing angle θ (\emptyset fixed)

Note: Optimum viewing angle with the naked eye and viewing angle θ at Cmax. Above are not always the same

Note 4: Definition of response time



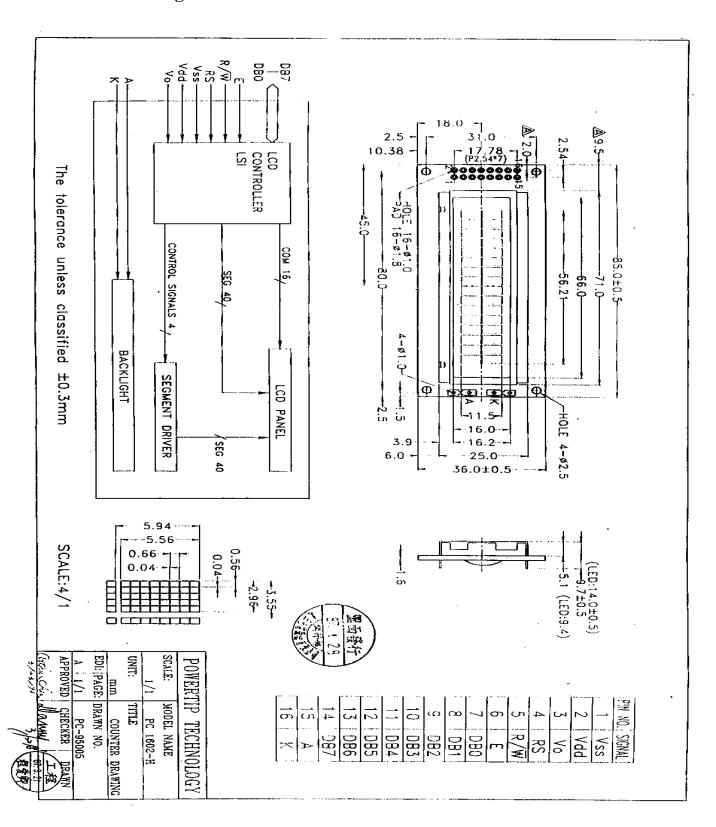
Note: Measured with a transmissive LCD panel which is displayed 1 cm²

 V_{LCD} : Operating voltage f_{FRM} : Frame frequency t_r : Response time (rise) t_f : Response time (fall)



2. MODULE STRUCTURE

2.1 Counter Drawing

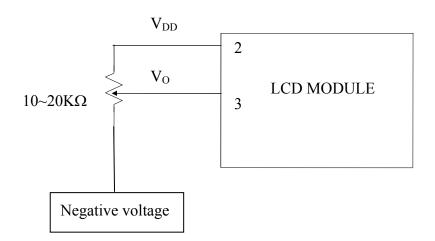




2.2 Interface Pin Description

Pin No.	Symbol	Function
1	Vss	Signal ground (GND)
2	Vdd	Power Supply for logic (VDD > VSS)
3	Vo	Operating Voltage for LCD (variable)
		Register Selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
5		R/W signal input is used to select the read/write mode
3	R/W	High = Read mode, Low = Write mode
6	Е	Start enable signal to read or write the data
7~10		Four low order bi-directional three-state data bus lines.
	DB0 ~ DB3	Used
		For data transfer between the MPU and the LCD module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	DB4~DB7	Used for data transfer between the MPU and the LCD
11/~14	DD4°DD7	module.
		DB7 can be used as a busy flag.
15	A	NC
16	K	NC

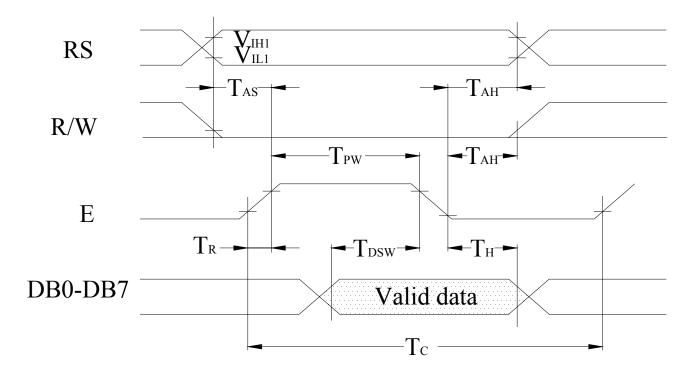
Contrast Adjust



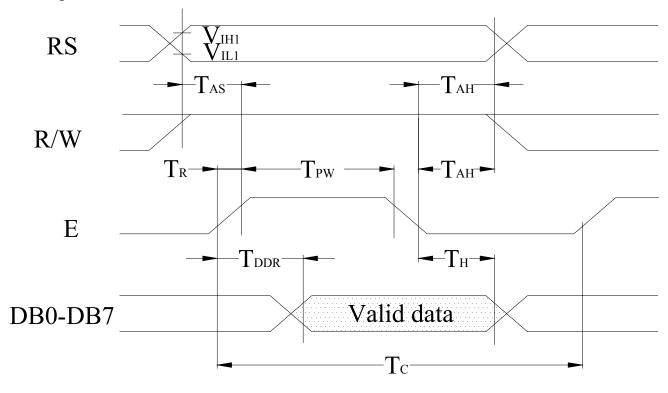


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



• Reading data from ST7066U to MPU





• Write Mode (Writing data from MPU to ST7066U)

 $(V_{DD}=+5V\pm10\%, V_{SS}=0V, Ta=25^{\circ}C)$

			(,	,
Symbol	Characteristics	Test Condition	Min.	Type	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T_{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T_{DSW}	Data Setup Time	Pins:DB0~DB7	40	-	-	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

• Read Mode (Reading data from ST7066U to MPU)

 $(V_{DD}=+5V+10\%, V_{SS}=0V, Ta=25^{\circ}C)$

			(1 DD	· 3 V <u>· </u> 10/0	, 155 01,	14 23 C)
Symbol	Characteristics	Test Condition	Min.	Type	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T_{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T_{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
T _H	Data Hold Time	Pins:DB0~DB7	10	-	-	ns



2.4 Display Command

				Ins	tructi	on C	ode					Description
Instructions	RS	R/W	DB	DB 6	DB 5	DB 4	DB 3	DB 2	DB 1	DB 0	Description	Time (270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC.	1.52ms
Return Home	0	0	0	0	0	0	0	0	1	×	Set DDRAM address to "00H" from AC and return cursor to it's original position if shifted. The contents of DDRAM are not changed.	1.52ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37us
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1 : entire display on C=1 : cursor on B=1 : cursor position on	37µs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	×	×	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	37/11S
Function Set	0	0	0	0	1	DL	N	F	×	×	DL: interface data is 8/4 bits NL: number of line is 2/1 F: font size is 5×11/5×8	37µs
Set CGRAM Address	0	0	0	1	AC 5	AC 4	AC 3	AC 2	AC	AC 0	Set CGRAM address in address counter.	37µs
Set DDRAM Address	0	0	1	AC 6	AC 5	AC 4	AC 3	AC 2	AC	AC 0	Set DDRAM address in address counter.	37µs



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	37µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	37µs

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Refer to Instruction Table for the list of each instruction execution time.



2.5 Character Pattern

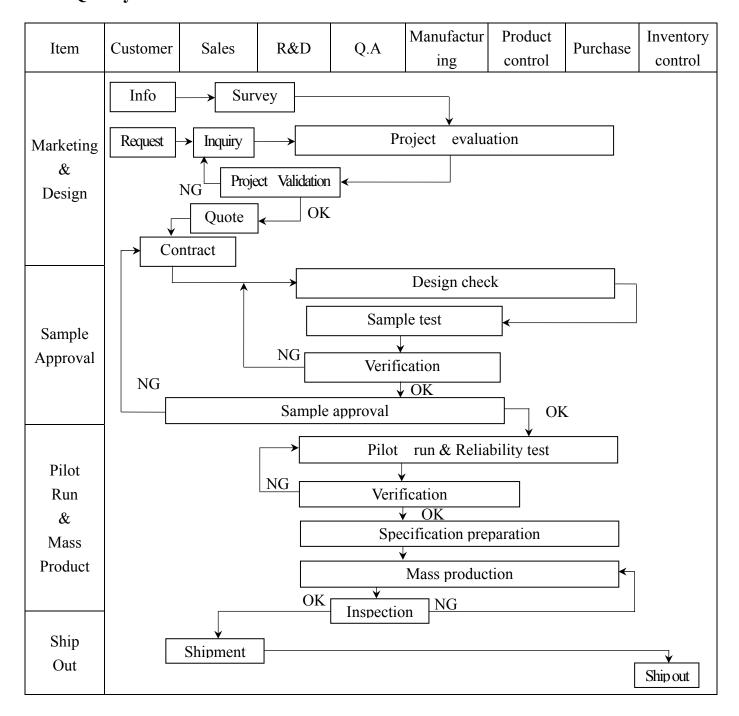
■ CHARACTER PATTERN(EB,WB)

		H	ligh	4-b	it (D	4to	D7)	of (Cha	ract	erC	ode	(H	exa	deci	mal)
		0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F
	0	CG RAM (1)	::::					=:	ļ:::-	·		-	•	ı.	H		-17
	1	CG RAM (2)	===	1	1		(3)	-===	-::-[-111	í		.]		`}·`	
	2	CG RAM (3)	"."	::	2			E	ļ		H	÷	-:-	00	===	::::	7
	3	CG RAM (4)		##			5	€	::::-	-#	::::		•		41	===	4
	4	CG RAM (5)	1 -	:	::		-T-		ŧ	-	-::-						0
	5	CG RAM (6)	I.	::- <u>:</u> :	===	E	 !	====	11	-	-	:E::	1 ::		æi	11	
	6	CG RAM (7)			€::	-	I.,.I	+	۱.,.۱	.ii		H	I _{I.}				!
4-bit (D0 to D3) of Character Code (Hexadecimal)	7	CG RAM (8)	_=	:=	7		Į,j		1,.,1	===		Fi.	> <		:**:	Ĭ	==
	8	CG RAM (1)	I	€.			\bowtie	ŀ'n	;×:		Ċ.	.;₽		-ŧ <u>:</u>		K	
	9	CG RAM (2)	 II)	9	I	¥	i	ایی:		-	:	≤	I	111	<i>.</i> 7.	
	Α	CG RAM (3)	\approx	:4:	#	.J	Z	.j	:: :						:	 !.	
Lower	В	CG RAM (4)			::	K	Е	k	-{	1	Fi		-:::	L	1	1,.33	-
	С	CG RAM (5)	:::::	:=	<(<u></u>	٠.,	1	i	1	A	8]:\$:-		•	4	
	D	CG RAM (6)	: : :					m]-	<u>:</u>	:::::		::::	::		M	
	E	CG RAM (7)		::	\geq	H	٠٠٠.	l-"i	٠	Ä							
	F	CG RAM (8)	≣						ش	ıä,	ċ.	:::::					

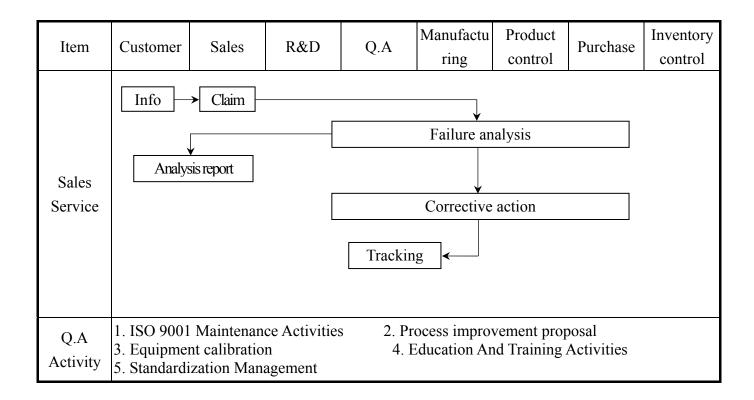


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level II •

Equipment: Gauge · MIL-STD · Powertip Tester · Sample ·

IQC Defect Level: Major Defect AQL 0.4; Minor Defect AQL 1.5 °

FQC Defect Level: 100% Inspection • OUT Going Defect Level: Sampling •

Specification:

1Part NumberThe part number is inconsistent with work order of productionN.C.2QuantityThe quantity is inconsistent with work order of productionN.C.3Electronic characteristics of LCM A=(L+W)÷2The display lacks of some patterns.N.C.4Missing line.N.C.There is no function.N.C.Output data is errorN.C.Material is different with work order of productionN.C.LCD is assembled in inverse directionN.C.Bezel is assembled in inverse directionN.C.Shadow is within LCD viewing area + 0.5 mmN.C.The diameter of dirty particle, A is > 0.4 mmN.C.Dirty particleDirty particle length is > 3.0 mm, and 0.01 mmN.C.Unally particleDisplay is without protective filmN.C.Conductive rubber is over bezel 1mmN.C.	
Electronic characteristics of LCM $A=(L+W)\div 2$ Appearance of LCD $A=(L+W)\div 2$ Appearance of LCD $A=(L+W)\div 2$ Dirty particle Electronic characteristics of LCM $A=(L+W)\div 2$ Dirty particle Electronic characteristics of LCM $A=(L+W)\div 2$ Dirty particle Electronic characteristics of LCM $A=(L+W)\div 2$ Dirty particle Electronic $A=(L+W)\div 2$ Missing line. The display lacks of some patterns. Missing line. N.C The size of missing dot, A is > 1/2 Dot size N.C There is no function. Output data is error N.C Material is different with work order of production N.C Electronic $A=(L+W)\div 2$ Dirty particle length is inverse direction N.C Shadow is within LCD viewing area + 0.5 mm N.C Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is > 3.0mm, and 0.01mm < width Solution $A=(L+W)\div 2$ Dirty particle length is over bezel 1mm	. Major
Blectronic characteristics of LCM $A=(L+W)\div 2$ Missing line. The size of missing dot, A is > 1/2 Dot size There is no function. Output data is error Material is different with work order of production LCD is assembled in inverse direction Bezel is assembled in inverse direction N.C Shadow is within LCD viewing area + 0.5 mm The diameter of dirty particle, A is > 0.4 mm N.C Dirty particle length is > 3.0mm, and 0.01mm < width ≤ 0.05 mm Display is without protective film Conductive rubber is over bezel 1 mm N.C	. Major
characteristics of LCM $A=(L+W)\div 2$ The size of missing dot, A is > 1/2 Dot size $A=(L+W)\div 2$ There is no function. $A=(L+W)\div 2$ There is no function. $A=(L+W)\div 2$ There is no function. $A=(L+W)\div 2$ $A=(L+W)\div 2$ The size of missing dot, A is > 1/2 Dot size $A=(L+W)\div 2$ There is no function. $A=(L+W)\div 2$ $A=(L+W)\div 2$ $A=(L+W)\div 2$ The diameter with work order of production $A=(L+W)\div 2$ $A=(L+W)\div 2$ The diameter of dirty particle, A is > 0.4 mm $A=(L+W)\div 2$	Major
The size of missing dot, A is > 1/2 Dot size There is no function. Output data is error Material is different with work order of production LCD is assembled in inverse direction N.C Shadow is within LCD viewing area + 0.5 mm N.C Shadow is within LCD viewing area + 0.5 mm N.C The diameter of dirty particle, A is > 0.4 mm N.C Dirty particle length is > 3.0mm, and 0.01mm < width ≤ 0.05 mm Display is without protective film Conductive rubber is over bezel 1 mm N.C	. Major
A= $(L+W)$ ÷2 There is no function. Output data is error N.C Material is different with work order of production LCD is assembled in inverse direction N.C Bezel is assembled in inverse direction N.C Shadow is within LCD viewing area + 0.5 mm N.C Shadow is within LCD viewing area + 0.5 mm N.C The diameter of dirty particle, A is > 0.4 mm N.C Dirty particle length is > 3.0mm, and 0.01mm < width ≤ 0.05 mm Display is without protective film N.C Conductive rubber is over bezel 1 mm	. Major
Output data is error Material is different with work order of production LCD is assembled in inverse direction N.C Bezel is assembled in inverse direction N.C Shadow is within LCD viewing area + 0.5 mm N.C Shadow is within LCD viewing area + 0.5 mm N.C The diameter of dirty particle, A is > 0.4 mm N.C Dirty particle length is > 3.0 mm, and 0.01 mm $<$ width ≤ 0.05 mm Display is without protective film N.C Conductive rubber is over bezel 1 mm	. Major
Appearance of LCD A=(L+W)÷2 Dirty particle LCD is assembled in inverse direction Bezel is assembled in inverse direction N.C. Shadow is within LCD viewing area + 0.5 mm N.C. The diameter of dirty particle, A is > 0.4 mm N.C. Dirty particle length is > 3.0mm, and 0.01mm < width ≤ 0.05 mm Display is without protective film Conductive rubber is over bezel 1 mm N.C. N.C	. Major
Appearance of LCD A= $(L+W)$ ÷2 Dirty particle	
Appearance of LCD A=(L+W)÷2 Dirty particle Appearance of LCD Dirty particle length is >3.0 mm, and 0.01 mm $<$ width >0.0 0 Dirty particle Dirty particle >0.05 mm Display is without protective film Conductive rubber is over bezel 1 mm N.C. N	
Appearance of LCD A= $(L+W)$ ÷2 Dirty particle Dirty particle length is >3.0mm, and 0.01mm N.C.	-
LCD A=(L+W)÷2 Dirty particle 0.05 mm Display is without protective film N.C Conductive rubber is over bezel 1 mm N.C	. Major
A= $(L+W)\div 2$ Dirty particle Solution is over bezel 1 mm N.C. N.C. N.C. N.C. N.C. N.C. N.C. N.	. Minor
Dirty particle Display is without protective film N.C. Conductive rubber is over hezel 1mm N.C.	. Minor
Dirty particle Conductive rubber is over hezel 1mm N.C.	Minor
(Including Polarizer exceeds over viewing area of LCD N.C	Minor
Area of hubble in polarizer A > 1 0mm, the number of	<u> </u>
bubble is >1 piece.	. Minor
0.4mm < Area of bubble in polarizer, A < 1.0mm, the	7.6
number of bubble is >4 pieces.	. Minor
Burned area or wrong part number is on PCB N.C	Major
The symbol, character, and mark of PCB are unidentifiable.	
The stripped solder mask, A is > 1.0mm N.C	Minor
0.3mm < stripped solder mask or visible circuit, A <	3.6
Appearance of $\begin{vmatrix} 1 & 0 \\ 1 & 0 \end{vmatrix}$ and the number is ≥ 4 pieces	. Minor
There is narticle between the circuits in solder mask N.C.	Minor
$A=(L+W)\div 2$ The circuit is peeled off or cracked N.C.	
There is any circuits risen or exposed. N.C.	Minor
0.2 mm $<$ Area of solder ball, A is ≤ 0.4 mm	7.6
The number of solder ball is ≥ 3 pieces	Minor
The magnitude of solder ball, A is > 0.4 mm. N.O.	Minor



NO	Item	Specification	Judge	Level
6		The shape of modeling is deformed by touching.		Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
	molding A=(L+W)÷2	Excessive epoxy: Diameter of modeling is $>$ 20mm or height is $>$ 2.5mm	N.G.	Minor
		The diameter of pinhole in modeling, A is >0.2mm.	N.G.	Minor
		The folding angle of frame must be $>45^{\circ} +10^{\circ}$	N.G.	Minor
7	Appearance of frame	The area of stripped electroplate in top-view of frame, A is > 1.0mm.	N.G.	Minor
/	$A=(L+W)\div 2$	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is >0.06mm. (Top view only)	N.G.	Minor
	F1 4 : 1	The color of backlight is nonconforming	N.G.	Major
	Electrical	Backlight can't work normally.	N.G.	Major
0	characteristic of backlight	The LED lamp can't work normally	N.G.	Major
8		The unsoldering area of pin for backlight, A is $> 1/2$ solder joint area.	N.G.	Minor
	$A=(L+W)\div 2$	The height of solder pin for backlight is >2.0mm	N.G.	Minor
	Assembly parts $A=(L+W)\div 2$	The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and surface of the PCB is floating > 0.7mm	N.G.	Minor
10		D>1/4W W D D D D Pad	N.G.	Minor
		End solder joint width, D' is >50% width of component termination or width of pad	N.G.	Minor
		Side overhang, D is >25% width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is $< 0.5 \text{mm}$.	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Condition				
1	High Temperature Storage	Storage at 80 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs				
2	Low Temperature Storage	Storage at -30 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs				
3	High Temperature /Humidity Storage	1.Storage 96~100 hrs 60±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4 hrs.				
4	Temperature Cycling	$-20^{\circ}\mathbb{C} \rightarrow 25^{\circ}\mathbb{C} \rightarrow 70^{\circ}\mathbb{C} \rightarrow 25^{\circ}\mathbb{C}$ $(30\text{mins}) (5\text{mins}) (30\text{mins}) (5\text{mins})$ 10 Cycle				
5	Vibration	10~55Hz (1 minute) 1.5mm X,Y and Z direction * (each 2hrs)				
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.			
7	Drop Test	Packing Weight (Kg) $0 \sim 45.4$ $45.4 \sim 90.8$ $90.8 \sim 454$ Over 454	Drop Height (cm) 122 76 61 46			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.